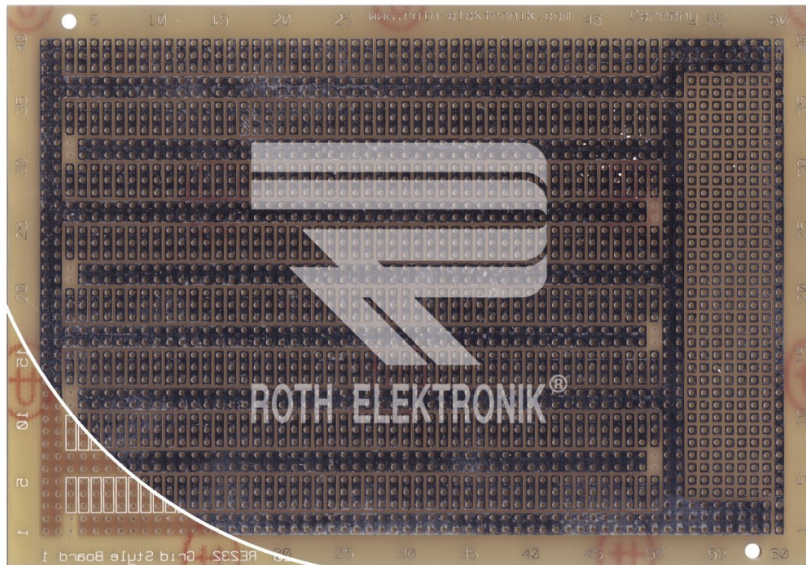


Prototyping Board for Dual Inline ICs (not in Europe-format)



RE232-LF

- EPOXY fibre-glass FR4 1.60 mm single-side 35 µm CU
- hot air leveling (HAL-leadfree)
- component printing on the component side
- hole spacing 2.54 mm x 2.54 mm
- 40 x 60 tracks of bored holes
- 3-hole lands
- 4 rows DIP IC grid 7.62 mm, 15.24 mm with 48 terminal pins
- hole dia 1.02 mm (0.40")
- max. working temperature 150° C (320°F)
- size 114.30 mm x 165.10 mm (4.5" x 6.5")